



In-situ TEM High Cycle Fatigue Response of Nanocrystalline Pt

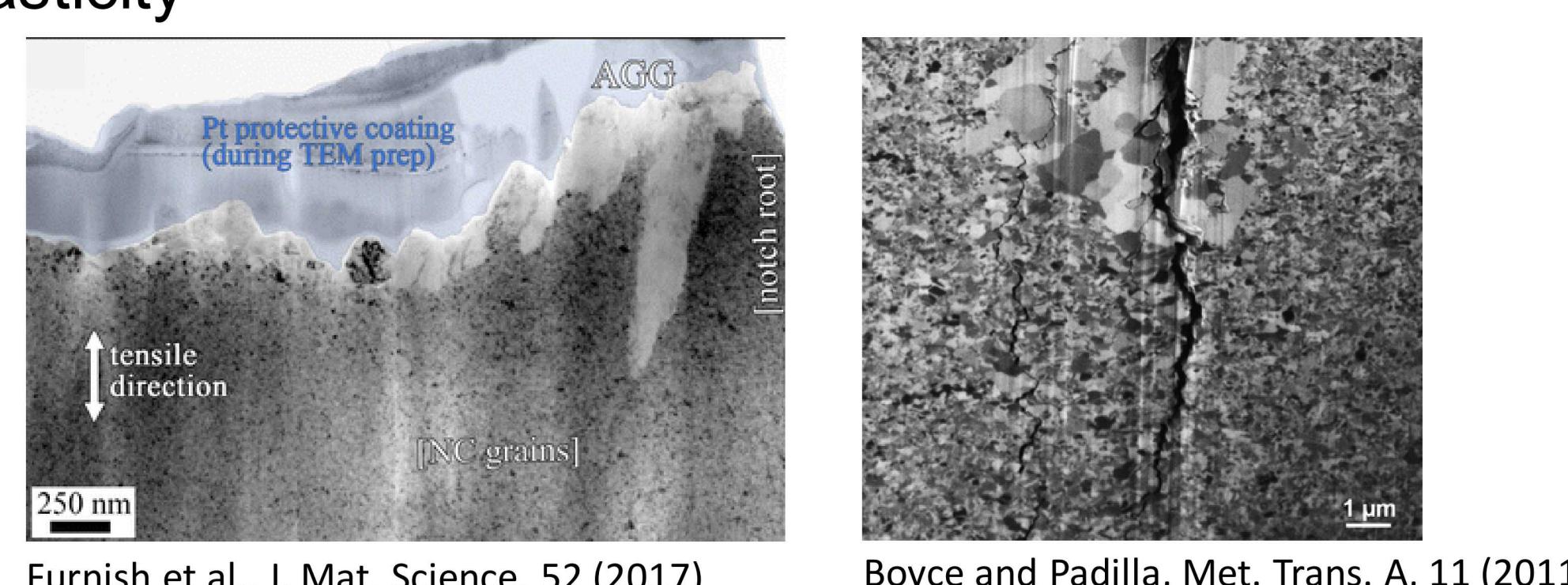
Christopher M. Barr, Nathan Heckman, Brad L. Boyce, and Khalid Hattar
Material, Chemical, and Physical Sciences, Sandia National Laboratories



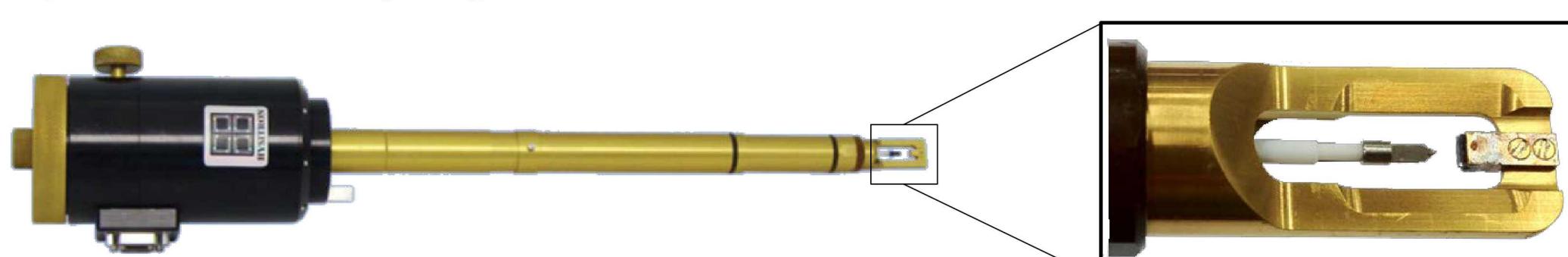
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Introduction:

- Nanocrystalline (NC) metals are typically have improved fatigue properties compared to coarse grain counterparts with higher endurance limit
- Nanoscale microstructural changes however occur with high cyclic fatigue loading
- Fatigue in NC metals can show deleterious and significant grain boundary migration, rotation, grain growth, and localized plasticity

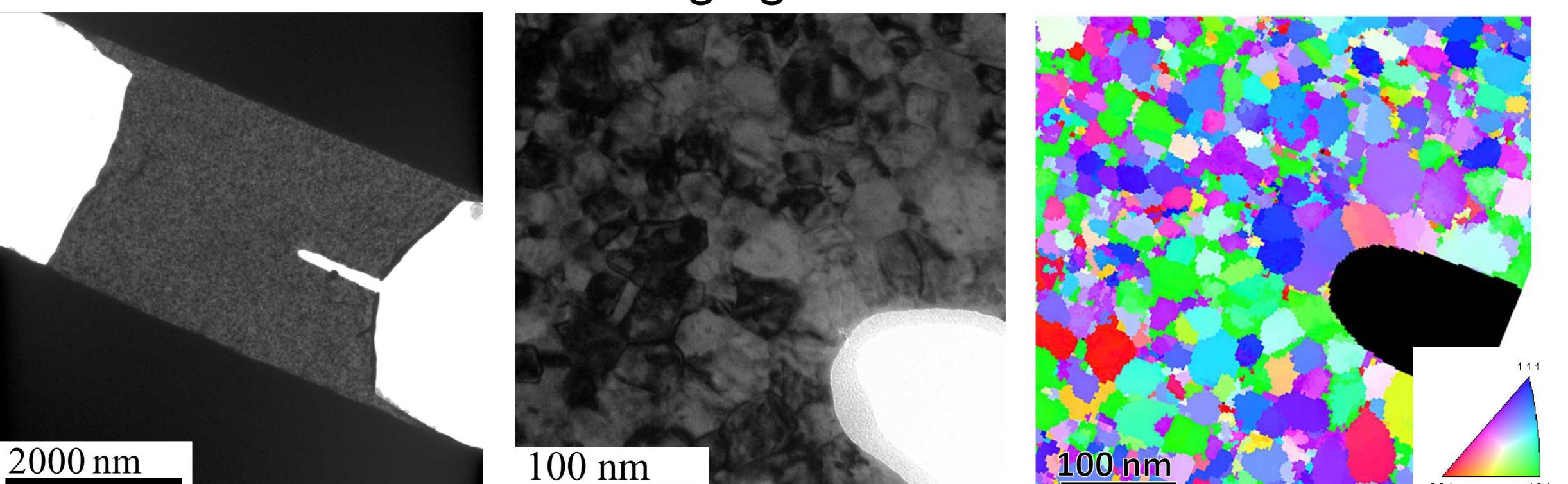


- In-situ TEM mechanical testing provides unique platform to explore underlying deformation mechanisms
- Quantitative mechanical testing with cyclic loading capabilities available via Bruker/Hysitron PI-95 stage at Sandia's I³TEM CINT facility



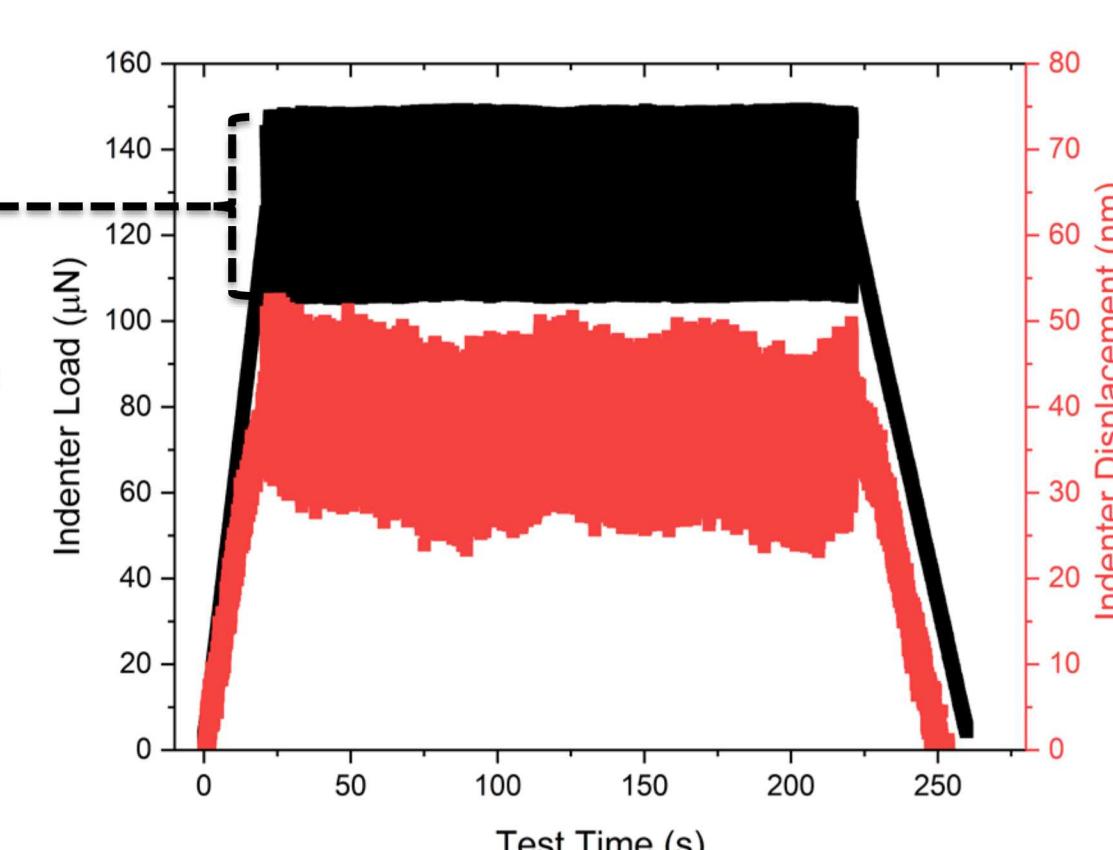
Notched Fatigue Conditions:

- FIB notch creates localized deformation and allows for higher resolution in-situ TEM imaging



- Precession electron diffraction (PED) provides ability to examine grain rotation and grain boundary misorientation evolution during fatigue propagation

- Mean load (P_{mean}) = 135 uN
- Amplitude load (P_{amp}) = 35 uN
- 200 Hz dynamic loading → image motion blur with standard 15 frames/s camera
- 13 cycles per individual frame

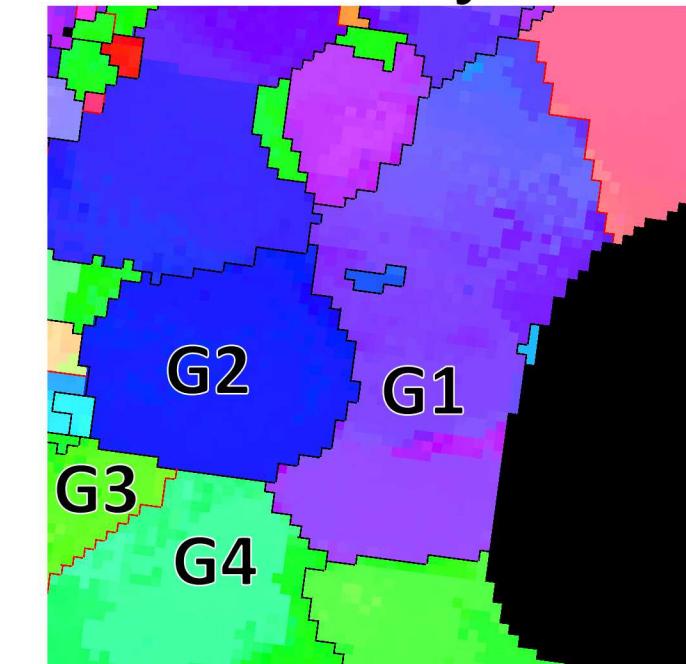


- PED orientation maps taken prior to test and during intermediate loading condition (120,000 total cycles)

Fatigue Crack Growth Rate:

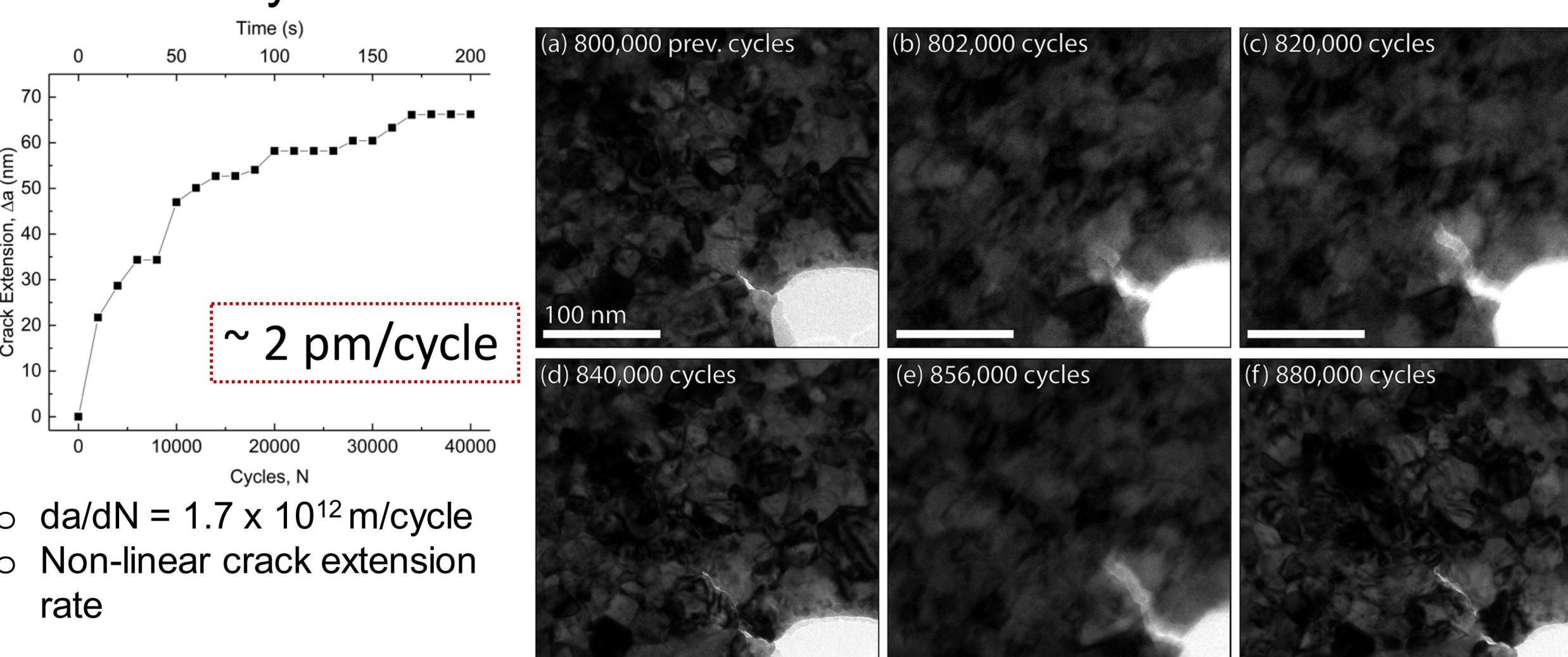
- Intermediate PED map (120,000 total cycles) indicates significant and quantifiable grain and grain boundary rotation

GB 3-4 (Twin Boundary Σ3)	Misorientation	Deviation from Ideal Σ3
Prior to Cyclic Loading	59.9° [1 1 1]	0.8 °
Crack Impinges GB at GB ₁₋₂	56.9 [7 7 6]	4.9 °



- Rapid propagation – transgranular between 800,000 to 854,000 total cycles

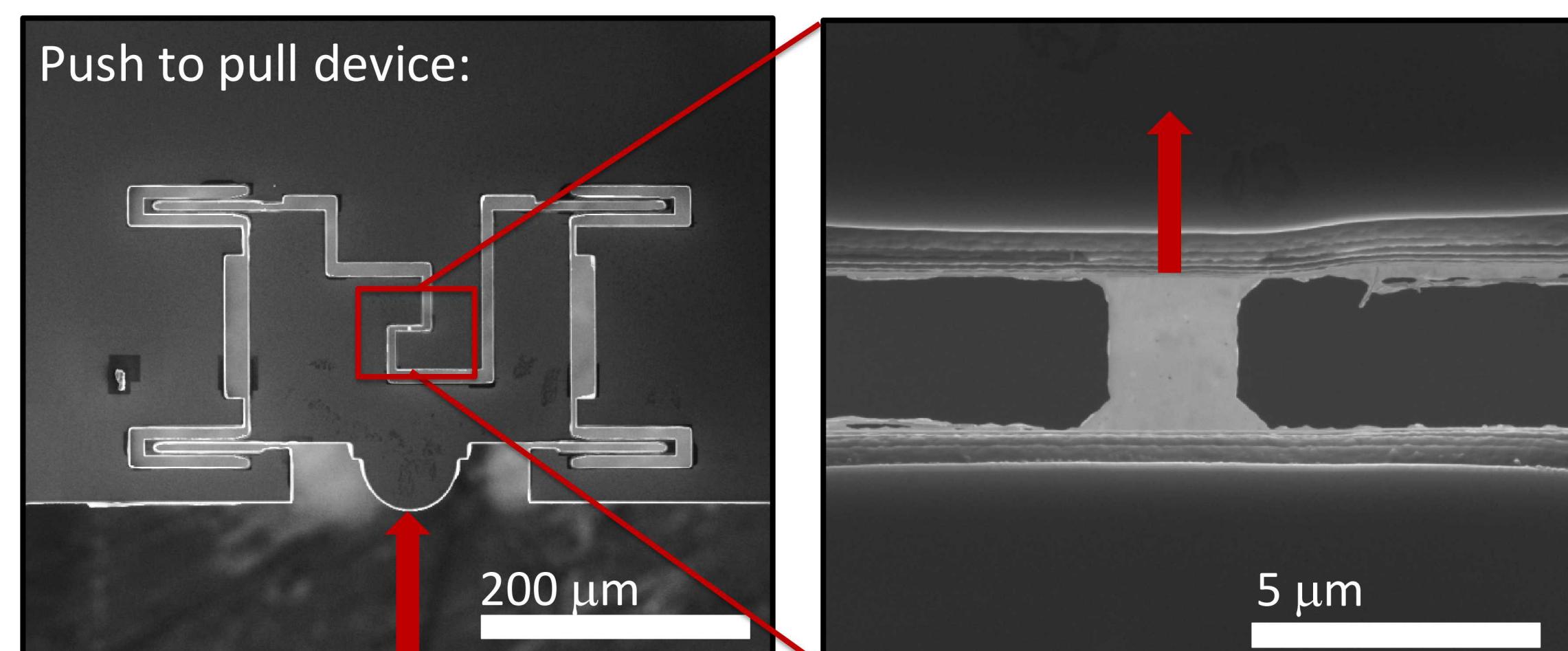
- After 854K cycles, cyclic loading crack impinges grain boundary



- No indications of previous deflected crack path – propagation continues closer to a mode I (normal to loading) direction
- Transgranular crack propagation has characteristics of "classic" zig-zag crack deflection

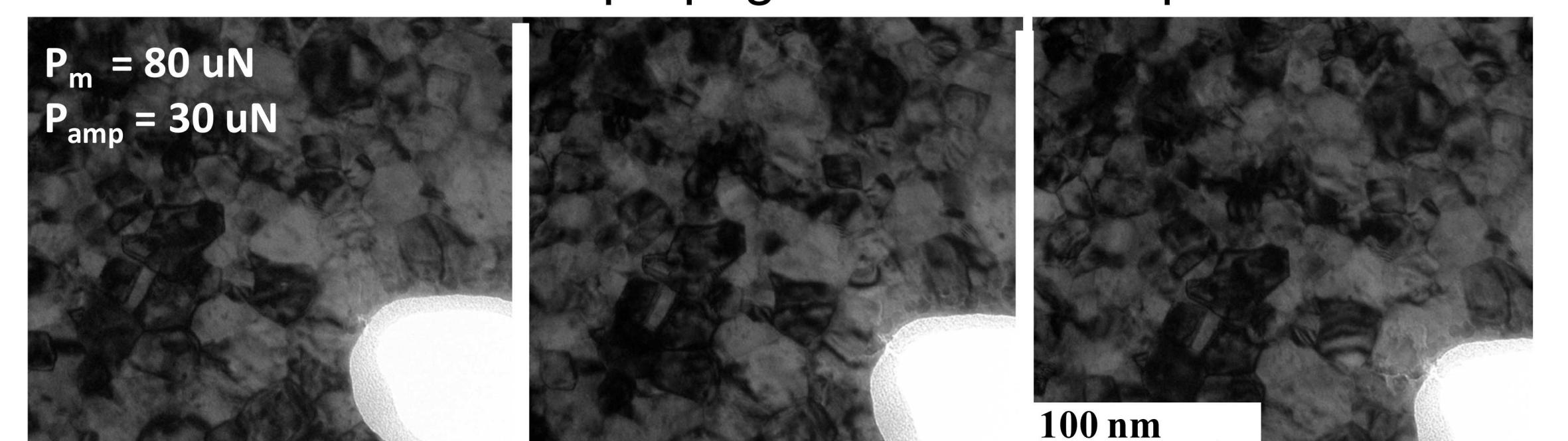
High Cycle Fatigue In-situ TEM Method:

- Push-to-Pull devices – microfabricated Si test frames
- $F_{\text{applied}} = F_{\text{measured}} - F_{\text{spring}}$
- Pt film (40 nm) sputter deposited on NaCl → floated onto devices
- FIB utilized for nanoscale machining → create small geometry for tension-tension fatigue → critical to minimize Ga imaging
- Indenter compression creates region of tension on sample

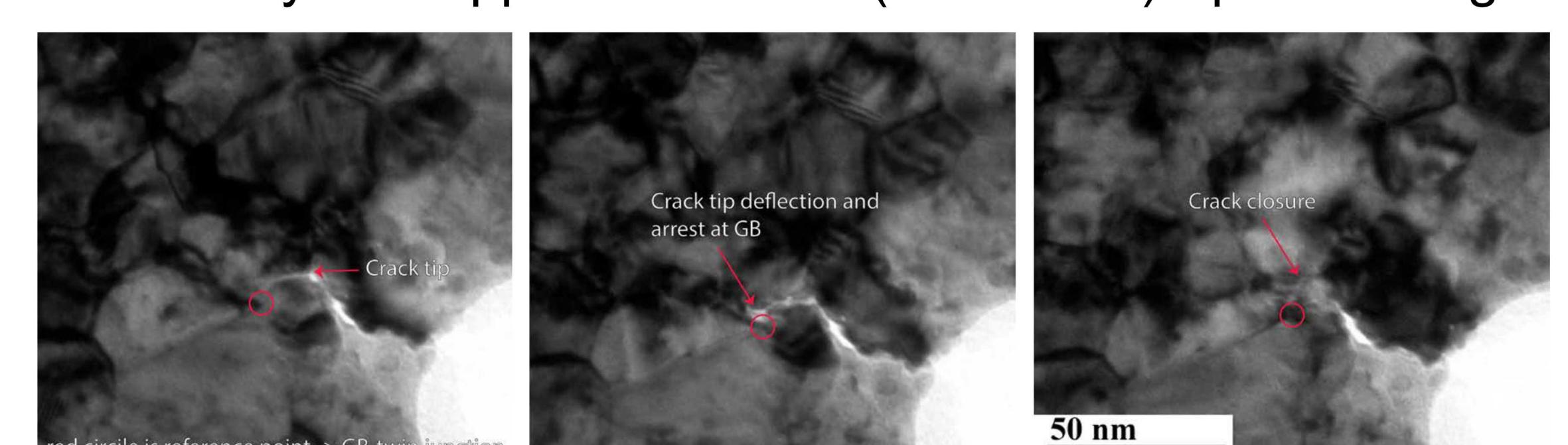


Crack Propagation and Deflection:

- Cracks initiation and propagation at notch tip

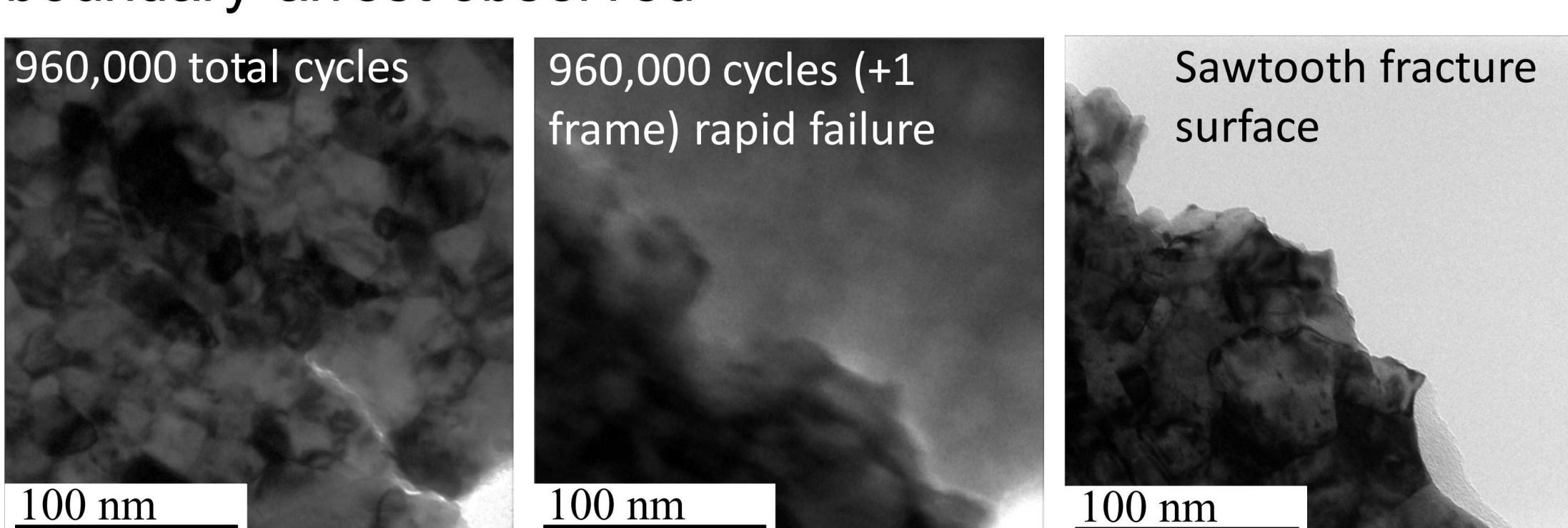


- Crack propagation transgranular
- Significant crack deflection away from mode I direction
- Deflected crack with mix-mode condition impinges grain boundary and appears to close (crack heal) upon loading



Key Outcomes and Future Directions:

- In-situ TEM fatigue tests utilizing the PI-95 nanoDMA setup provides a wealth of new opportunities for understanding nanoscale microstructure evolution under dynamic mechanical testing → 2D materials, novel architectures
- Crack initiation, transgranular propagation and grain boundary arrest observed



- Unique crack healing event observed during crack deflection away from mode I conditions
- Localized deformation (grain rotation and grain boundary misorientation change) quantified via PED orientation analysis